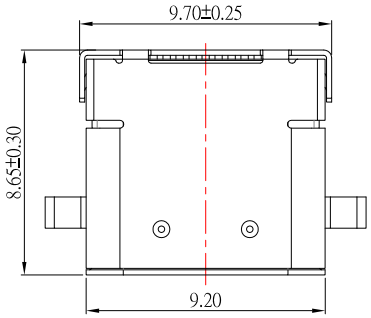
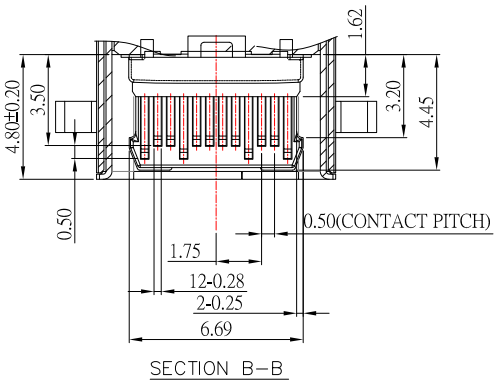
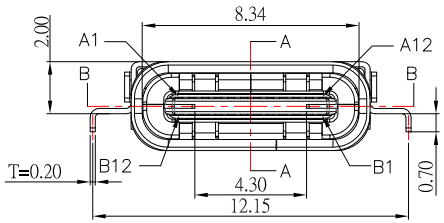


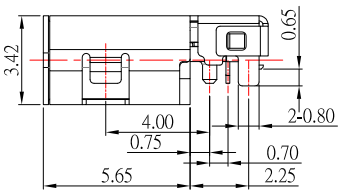



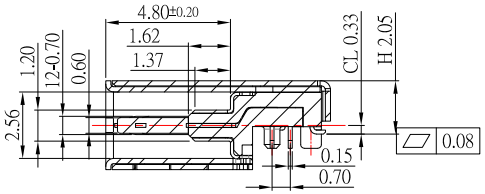

SECTION B–B

USB TYPE-C FULL-FEATURED RECEPTACLE INTERFACE PIN ASSIGNMENTS

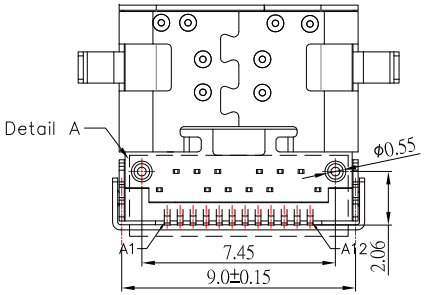
| PIN | Signal Name | Description | PIN | Signal Name | Description |
|---|---|---|---|---|---|
| A1 | GND | Ground return | B12 | GND | Ground return |
| A2 | SSTXp1 | Positive half of first SuperSpeed TX differential pair | B11 | SSRXp1 | Positive half of first SuperSpeed RX differential pair |
| A3 | SSTXn1 | Negative half of first SuperSpeed TX differential pair | B10 | SSRXn1 | Negative half of first SuperSpeed RX differential pair |
| A4 | VBUS | Bus Power | B9 | VBUS | Bus Power |
| A5 | CC1 | Configuration Channel | B8 | SBU2 | Sideband Use (SBU) |
| A6 | Dp1 | Positive half of the USB 2.0 differential pair-Position 1 | B7 | Dn2 | Negative half of the USB 2.0 differential pair-Position 2 |
| A7 | Dn1 | Negative half of the USB 2.0 differential pair-Position 1 | B6 | Dp2 | Positive half of the USB 2.0 differential pair-Position 2 |
| A8 | SBU1 | Sideband Use(SBU) | B5 | CC2 | Configuraation Channel |
| A9 | VBUS | Bus Power | B4 | VBUS | Bus Power |
| A10 | SSRXn2 | Negative half of second SuperSpeed RX differential pair | B3 | SSTXn2 | Negative half of second SuperSpeed TX differential pair |
| A11 | SSRXp2 | Positive half of second SuperSpeed RX differential pair | B2 | SSTXp2 | Positive half of second SuperSpeed TX differential pair |
| A12 | GND | Ground return | B1 | GND | Ground return |

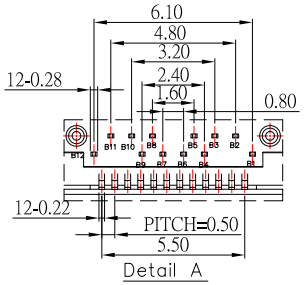


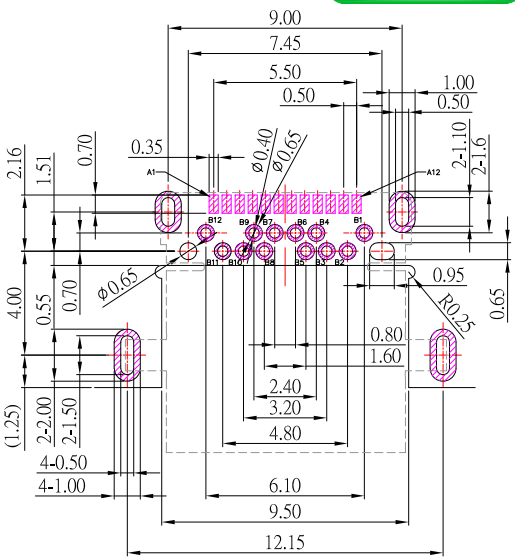




SECTION A–A




Detail A




RECOMMENDED P.C.B. LAYOUT

## SPECIFICATIONS

**Electrical:**

1.Rating: 5.0 A

2.Dielectric Withstand Voltage: 100V AC

3.Contact Resistance: 40 mΩ Max

4.Insulation Resistance: 100 MΩ Min

**Mechanical:**

1.Connector Mate and Unmate Force

1.1 Mate force: 5~20 N

1.2 Unmate force: 8~20 N

**Material:**

1.Housing: LCP

2.Contact: C7025

3.Shell: SUS

**Finish:**

1.Contact: Plated Gold in Mating Area ;
Gold Plated on Solder Balls ;
Nickel under plated overall

2.Shell: Nickel under Plated surface layer

| ITEM NO. | DESCRIPTION | DRAWN | DATE |
|---|---|---|---|
| 3 | 新增PCB LAYOUT尺寸 | Jack | 121223 |
| 2 | 更新圖面 | Jack | 102623 |
| 1 | 更新底部樣式 | Jack | 090123 |

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2; Above 5 ~ 15 ±0.3; Above 15 ~ 30 ±0.4; Above 30 ~ 50 ±0.5; Angle ±0.3°

3RD. ANGEL'S | UNITS MM

| | | | |
|---|---|---|---|
| DRAWN BY: Jack Lu | DATE 12/12/23 | MAT'L | |
| CHECKED BY: Jacky Chen | DATE 12/12/23 | FINISH | |
| APPROVED BY: Tony Kao | DATE 12/12/23 | SCALE 1 : 1 | SHEET NO. 1 of 1 |

| | | | |
|---|---|---|---|
| TITLE | CONNECTOR | | |
| MODLE | USB4 GEN 3 TYPE CF Mid Mount CH0.33mm 3u" | | |
| DWG NO. | SBC-240M23H-451-S410 | SIZE | A4 |
| PART NO. | SBC-240M23H-451-S410 | VER | R3 |